# FQP2N60/FQPF2N60

## 600V,2A N-Channel MOSFET

### General Description

The FQP2N60 & FQPF2N60 have been fabricated using an advanced high voltage MOSFET process that is designed to deliver high levels of performance and robustness in popular AC-DC applications.
By providing low $R_{DS(on)}$, $C_{iss}$ and $C_{rss}$ along with guaranteed avalanche capability these parts can be adopted quickly into new and existing offline power supply designs.

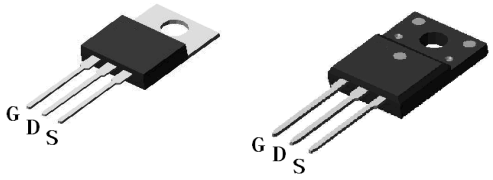
### Product Summary

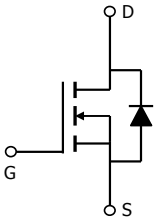
| | |
|---|---|
| $V_{DS}$ | 700V@150℃ |
| $I_D$ (at $V_{GS}$=10V) | 2A |
| $R_{DS(ON)}$ (at $V_{GS}$=10V) | < 4.4Ω |

100% UIS Tested
100% $R_g$ Tested

RoHS Compliant

TO-220 Top View TO-220F




**Absolute Maximum Ratings $T_A$=25℃ unless otherwise noted**

| Parameter | | Symbol | FQP2N60 | FQPF2N60 | Units |
|---|---|---|---|---|---|
| Drain-Source Voltage | | $V_{DS}$ | 600 | | V |
| Gate-Source Voltage | | $V_{GS}$ | ±30 | | V |
| Continuous Drain Current | $T_C$=25℃ | $I_D$ | 2 | 2* | A |
| | $T_C$=100℃ | | 1.7 | 1.7* | |
| Pulsed Drain Current [C] | | $I_{DM}$ | 8 | | |
| Avalanche Current [C] | | $I_{AR}$ | 2 | | A |
| Repetitive avalanche energy [C] | | $E_{AR}$ | 60 | | mJ |
| Single plused avalanche energy [G] | | $E_{AS}$ | 120 | | mJ |
| Peak diode recovery dv/dt | | dv/dt | 5 | | V/ns |
| Power Dissipation [B] | $T_C$=25℃ | $P_D$ | 74 | 31 | W |
| | Derate above 25°C | | 0.6 | 0.25 | W/ °C |
| Junction and Storage Temperature Range | | $T_J$, $T_{STG}$ | -55 to 150 | | ℃ |
| Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds | | $T_L$ | 300 | | ℃ |

**Thermal Characteristics**

| Parameter | Symbol | FQP2N60 | FQPF2N60 | Units |
|---|---|---|---|---|
| Maximum Junction-to-Ambient [A,D] | $R_{\theta JA}$ | 65 | 65 | ℃/W |
| Maximum Case-to-sink [A] | $R_{\theta CS}$ | 0.5 | -- | ℃/W |
| Maximum Junction-to-Case | $R_{\theta JC}$ | 1.7 | 4 | ℃/W |

* Drain current limited by maximum junction temperature.

**Electrical Characteristics ($T_J$=25℃ unless otherwise noted)**

| Symbol | Parameter | Conditions | Min | Typ | Max | Units |
|---|---|---|---|---|---|---|
| **STATIC PARAMETERS** | | | | | | |
| $BV_{DSS}$ | Drain-Source Breakdown Voltage | $I_D$=250μA, $V_{GS}$=0V, $T_J$=25℃ | 600 | | | V |
| | | $I_D$=250μA, $V_{GS}$=0V, $T_J$=150℃ | | 700 | | |
| $BV_{DSS}$ /ΔTJ | Zero Gate Voltage Drain Current | ID=250μA, VGS=0V | | 0.56 | | V/ °C |
| $I_{DSS}$ | Zero Gate Voltage Drain Current | $V_{DS}$=600V, $V_{GS}$=0V | | | 1 | μA |
| | | $V_{DS}$=480V, $T_J$=125℃ | | | 10 | |
| $I_{GSS}$ | Gate-Body leakage current | $V_{DS}$=0V, $V_{GS}$=±30V | | | ±100 | nA |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS}$=5V $I_D$=250μA | 3 | 4 | 4.5 | V |
| $R_{DS(ON)}$ | Static Drain-Source On-Resistance | $V_{GS}$=10V, $I_D$=1A | | 3.6 | 4.4 | Ω |
| $g_{FS}$ | Forward Transconductance | $V_{DS}$=40V, $I_D$=1A | | 3.5 | | S |
| $V_{SD}$ | Diode Forward Voltage | $I_S$=1A,$V_{GS}$=0V | | 0.79 | 1 | V |
| $I_S$ | Maximum Body-Diode Continuous Current | | | | 2 | A |
| $I_{SM}$ | Maximum Body-Diode Pulsed Current | | | | 8 | A |
| **DYNAMIC PARAMETERS** | | | | | | |
| $C_{iss}$ | Input Capacitance | $V_{GS}$=0V, $V_{DS}$=25V, f=1MHz | 215 | 270 | 325 | pF |
| $C_{oss}$ | Output Capacitance | | 23 | 29 | 35 | pF |
| $C_{rss}$ | Reverse Transfer Capacitance | | 2.2 | 2.8 | 3.4 | pF |
| $R_g$ | Gate resistance | $V_{GS}$=0V, $V_{DS}$=0V, f=1MHz | 3.5 | 4.4 | 6.6 | Ω |
| **SWITCHING PARAMETERS** | | | | | | |
| $Q_g$ | Total Gate Charge | $V_{GS}$=10V, $V_{DS}$=480V, $I_D$=2A | | 9.5 | 11.4 | nC |
| $Q_{gs}$ | Gate Source Charge | | | 1.9 | 2.3 | nC |
| $Q_{gd}$ | Gate Drain Charge | | | 4.7 | 5.6 | nC |
| $t_{D(on)}$ | Turn-On DelayTime | $V_{GS}$=10V, $V_{DS}$=300V, $I_D$=2A, $R_G$=25Ω | | 17.2 | | ns |
| $t_r$ | Turn-On Rise Time | | | 14.3 | | ns |
| $t_{D(off)}$ | Turn-Off DelayTime | | | 27 | | ns |
| $t_f$ | Turn-Off Fall Time | | | 17 | | ns |
| $t_{rr}$ | Body Diode Reverse Recovery Time | $I_F$=2A,dI/dt=100A/μs,$V_{DS}$=100V | | 154 | 185 | ns |
| $Q_{rr}$ | Body Diode Reverse Recovery Charge | $I_F$=2A,dI/dt=100A/μs,$V_{DS}$=100V | | 0.80 | 1 | μC |

A. The value of $R_{\theta JA}$ is measured with the device in a still air environment with $T_A$=25℃.

B. The power dissipation $P_D$ is based on $T_{J(MAX)}$=150℃, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$=150℃, Ratings are based on low frequency and duty cycles to keep initial $T_J$ =25℃.

D. The $R_{\theta JA}$ is the sum of the thermal impedence from junction to case $R_{\theta JC}$ and case to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300 μs pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-case thermal impedence which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(MAX)}$=150℃. The SOA curve provides a single pulse ratin g.

G. L=60mH, $I_{AS}$=2A, $V_{DD}$=150V, $R_G$=25Ω, Starting $T_J$=25℃

## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

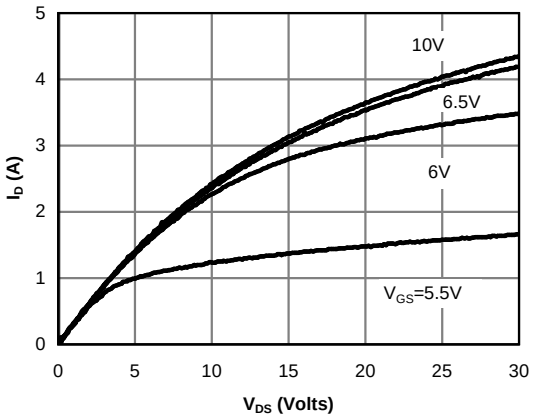



**Fig 1: On-Region Characteristics**

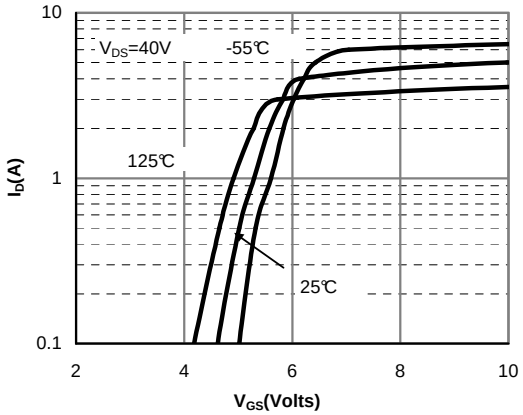



**Figure 2: Transfer Characteristics**

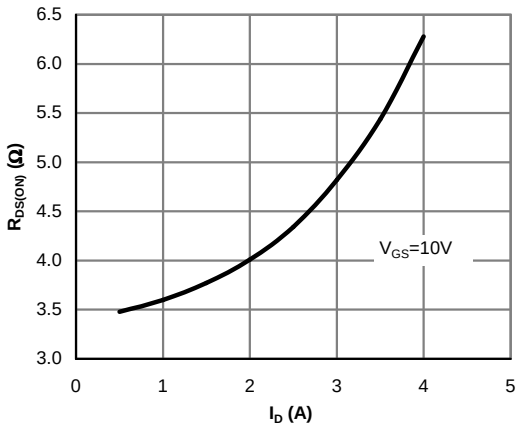



**Figure 3: On-Resistance vs. Drain Current and Gate Voltage**

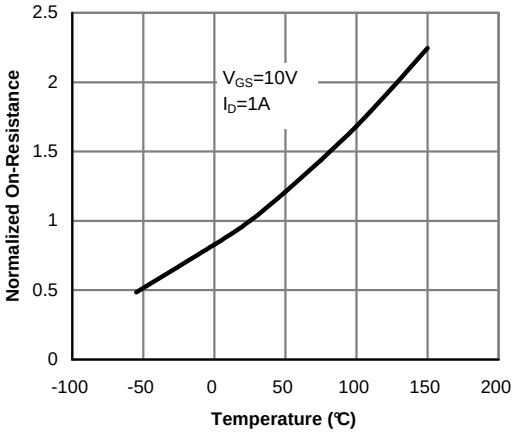



**Figure 4: On-Resistance vs. Junction Temperature**

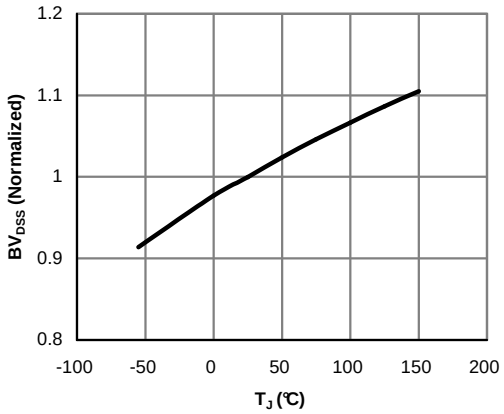



**Figure 5:Break Down vs. Junction Temparature**

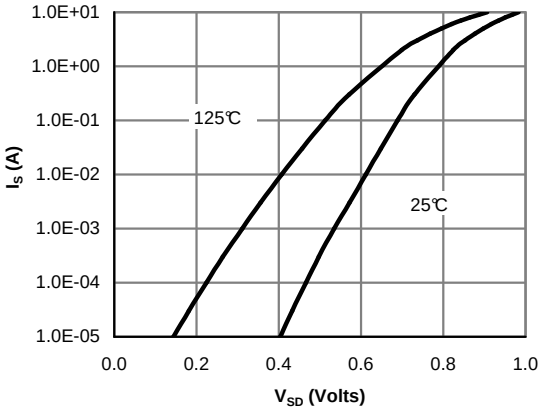



**Figure 6: Body-Diode Characteristics (Note E)**

## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

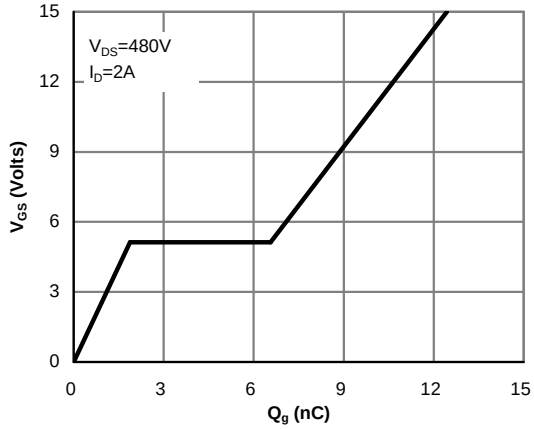



**Figure 7: Gate-Charge Characteristics**

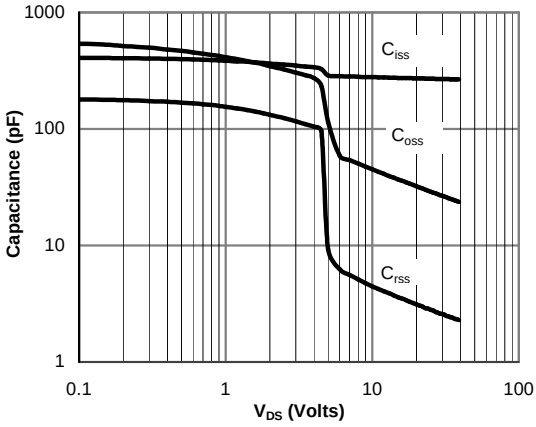



**Figure 8: Capacitance Characteristics**

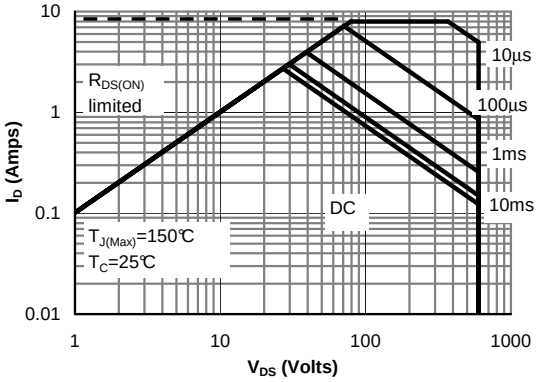



**Figure 9: Maximum Forward Biased Safe Operating Area for AOT2N60 (Note F)**

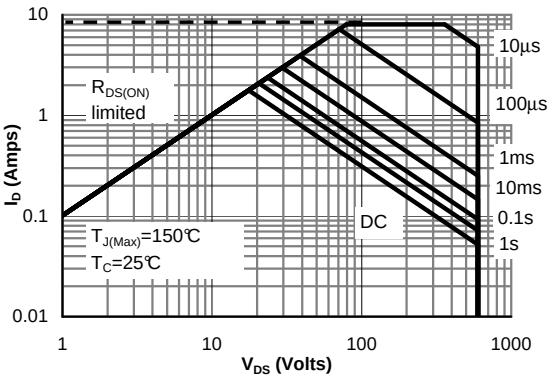



**Figure 10: Maximum Forward Biased Safe Operating Area for AOTF2N60 (Note F)**

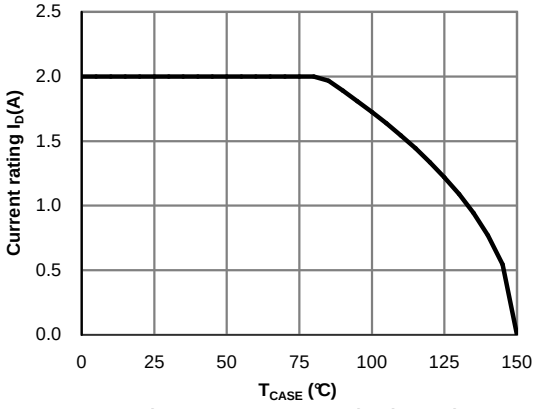



**Figure 11: Current De-rating (Note B)**

## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

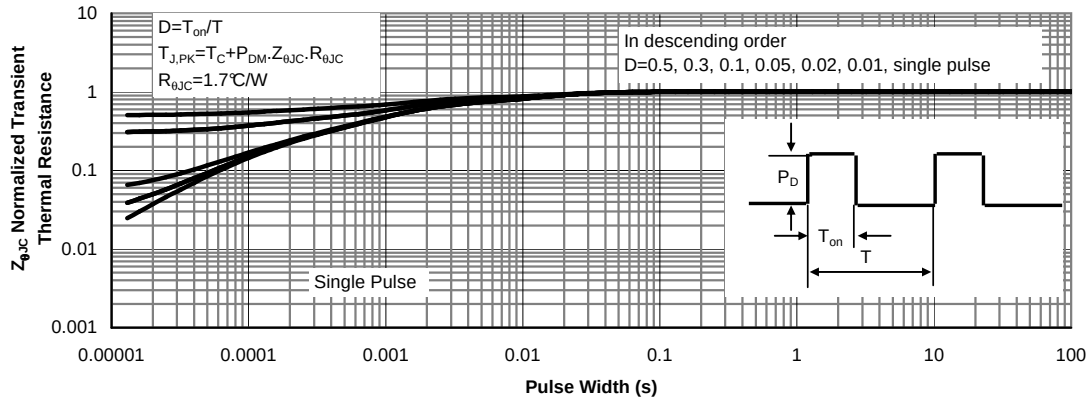



**Figure 12: Normalized Maximum Transient Thermal Impedance for AOT2N60 (Note F)**

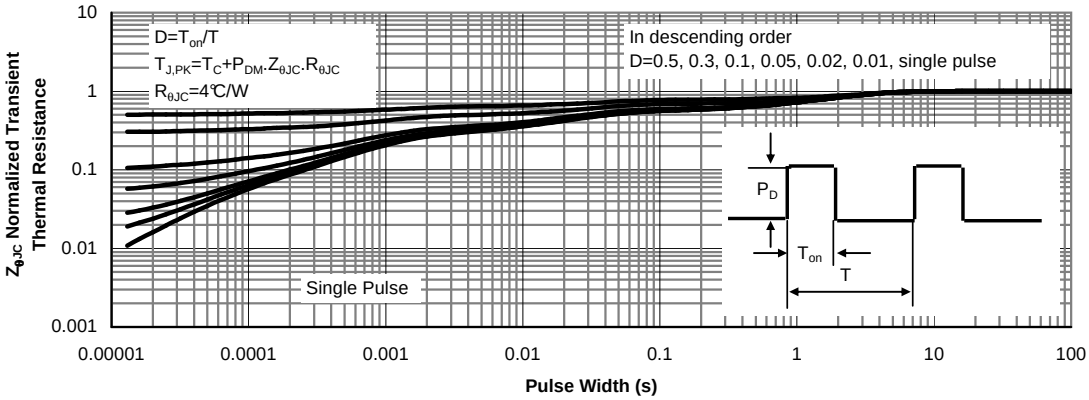
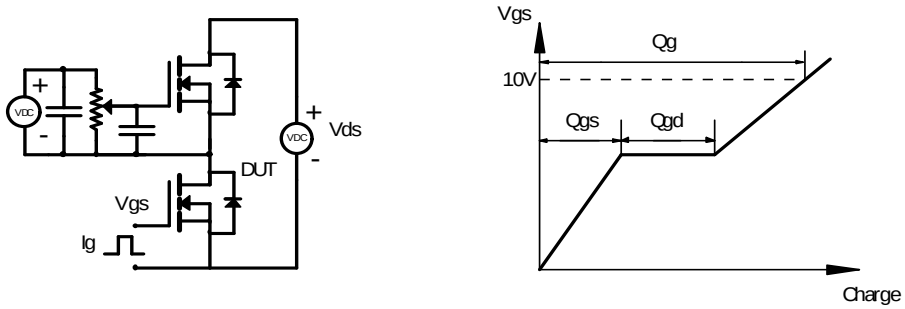
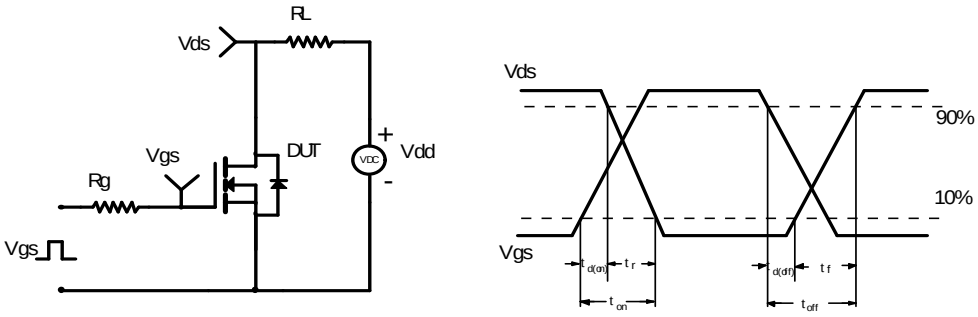



**Figure 13: Normalized Maximum Transient Thermal Impedance for AOTF2N60 (Note F)**

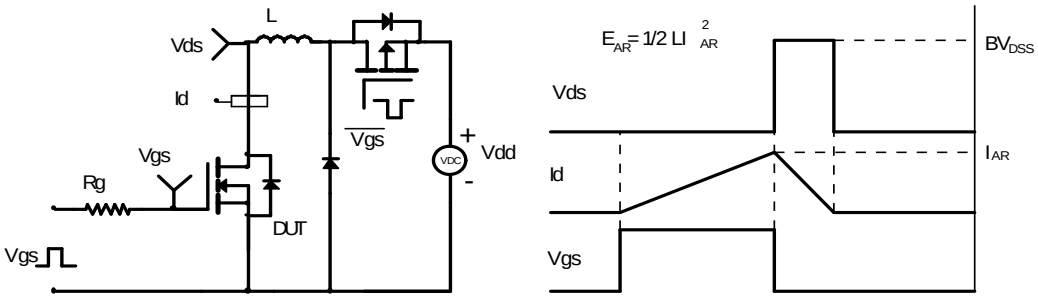
Gate Charge Test Circuit & Waveform




Resistive Switching Test Circuit & Waveforms




Unclamped Inductive Switching (UIS) Test Circuit & Waveforms




Diode Recovery Test Circuit & Waveforms